PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2975221

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
NACHIKET R. RARVIKAR	06/19/2014
JAMES C. MATAYABAS JR.	08/08/2014
AKSHAY MATHKAR	06/20/2014

RECEIVING PARTY DATA

Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BOULEVARD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14229785

CORRESPONDENCE DATA

Fax Number: (408)720-8383

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 408 720-8300
Email: teresa_mattox@bstz.com
Correspondent Name: MISSION/BSTZ BLAKELY SOKOLOFF TAYLOR & Z
Address Line 1: 1279 OAKMEAD PARKWAY
Address Line 4: SUNNYVALE, CALIFORNIA 94085-4040

ATTORNEY DOCKET NUMBER:	42P62735
NAME OF SUBMITTER:	TERESA MATTOX
SIGNATURE:	/TERESA MATTOX/
DATE SIGNED:	08/08/2014

Total Attachments: 6
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Attorney Docket No.: 42P62735

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

NACHIKET R. RARAVIKAR, JAMES C. MATABYABAS, JR., AKSHAY MATHKAR

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

LPS SOLDER PASTE BASED LOW COST FINE PITCH POP INTERCONNECT SOLUTIONS

(I hereby authorize and request my attorney, associated with customer number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on March 28, 2014 as

USA Application Number 14/229,785 and
COUNTRY or International Office

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and

the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Nachiket R. ~~Rarvikar~~ Raravikar	June 19, 2014 **Date signed**
James C. Matayabas, Jr.	**Date signed**
Akshay Mathkar	**Date signed**

Attorney Docket No.: 42P62735

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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Nachiket R. Rarvikar	**Date signed**
	8/8/2014
James C. Matayabas, Jr.	**Date signed**
Akshay Mathkar	**Date signed**

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Nachiket R. Rarvikar	**Date signed**
James C. Matayabas, Jr.	**Date signed**
	6/20/2014
Akshay Mathkar	**Date signed**